

TECHNICAL DATA SHEET 2/6				
MALE STRA	AIGHT RECE	РСВ	R222.508.700	
SMT TYPE	E - SMOOTH	500	Series : SMP	
PA	<u>CKAGING</u>	SPECIFICATION		
Standard 500	Unit -	Other Contact us		
ELECTRICAL	CHARACTER	<u>ENVIRONMENTAL</u>		
VSWR1.15*+0,0000Insertion loss0.12RF leakage- (NAVoltage rating335Dielectric withstanding voltage500		GHz x F(GHz) Maxi √F(GHz) dB Maxi - F(GHz)) dB Maxi Veff Maxi	Operating temper Hermetic seal Panel leakage	rature -65/+165 ° C NA Atm.cm3/s NA
			OTHER CHARACTERISTICS	
Axial force – Opposite end TorqueNARecommended torque Mating Panel nutNA		N mini N mini N.cm mini N.cm N.cm Cycles mini	Assembly instruction Others : Compliant with MIL-STD-348 *At 12.4GHz - Performance strongly depends on lay out and pcb material	
Issue : 0914 C In the effort to improve our p necessary.	roducts, we reserve	the right to make cha	anges judged to be	

TECHNICAL DATA SHEET

MALE STRAIGHT RECEPTACLE FOR PCB

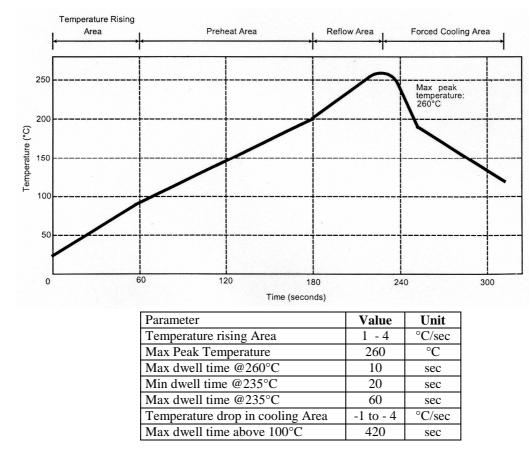
SMT TYPE - SMOOTH BORE - REEL 500

Series : SMP

R222.508.700

SOLDER PROCEDURE

- Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux. We advise a thickness of 150 μm. Verify that the edges of the zone are clean.
- Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
 Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.
- Soldering by infra-red reflow.
 Below, please find the typical profile to use.
- 4. Cleaning of printed circuit boards.
- 5. Checking of solder joints and position of the component by visual inspection.



TEMPERATURE PROFILE

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TECHNICAL DATA SHEET

MALE STRAIGHT RECEPTACLE FOR PCB

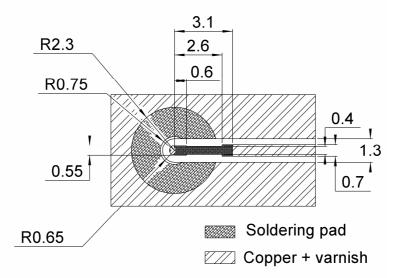
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RECOMMENDED PAD DIMENSIONS:

Substrate: RT5880 thickness 0.254mm, with copper layer 35µm on both sides: Add vias between both sides along upper ground plane according to engineering practise



Substrate: RO4350 thickness 0.254mm, with copper layer 35µm on both sides: Add vias between both sides along upper ground plane according to engineering practise

